IN THE CLAIMS:

1. (Previously Presented) A curable silicone composition comprising:

(A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings:

$$[R^1{}_3SiO_{1/2}]_a[R^2{}_2SiO_{2/2}]_b[R^3SiO_{3/2}]_c \qquad (1)$$

where R^1, R^2, and R^3 are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of R^3 are aryl groups; $a + b + c = 1$; on average, "a" satisfies the following condition: $0 \leq a \leq 0.8$; on average, "b" satisfies the following condition: $0 \leq b \leq 0.8$; and, on average, "c" satisfies the following condition: $0.2 \leq c \leq 1.0$;

(B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups, where said linear-chain organopolysiloxane is represented by the following formula (2):

$$R^7{}_3SiO(R^8{}_2SiO)_mSiR^7{}_3 \qquad (2)$$

where R^7 and R^8 may be the same or different and represent univalent organic groups of which, at least two are univalent organic groups having phenolic hydroxyl groups; and "m" is an integer having a value of 0 to 1000; and

(C) a curing accelerator.

2. (Original) The curable silicone composition of Claim 1, further comprising a filler (D).

3. (Previously Presented) The curable silicone composition of Claim 1, where component (A) is liquid.

4. (Previously Presented) The curable silicone composition of Claim 1, where in the siloxane unit formula (1), $0 < a \leq 0.8$; and b=0.

5. (Cancelled).

6. (Previously Presented) The curable silicone composition of Claim 1, where component (B) is an organopolysiloxane represented by the following formula (4):

$$Z\text{-}(CH_3)_2SiO(CH_3)_2Si\text{-}Z \qquad (4)$$

where Z is 3-(m-hydroxyphenyl)propyl group.

7. (Previously Presented) The curable silicone composition of Claim 1, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).

8. (Previously Presented) The curable silicone composition of Claim 1, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.

9. (Previously Presented) The curable silicone composition of Claim 1, which is in a liquid or a paste-like form.

10. (Previously Presented) A cured product obtained by curing the curable silicone composition according to Claim 1.

11. (Cancelled).

12. (Previously Presented) The curable silicone composition of Claim 2, where component (A) is liquid.

13. (Previously Presented) The curable silicone composition of Claim 2, where in the siloxane unit formula (1), $0 < a \leq 0.8$; and b=0.

14. (Cancelled).

15. (Previously Presented) The curable silicone composition of Claim 2, where component (B) is an organopolysiloxane represented by the following formula (4):

$$Z\text{-}(CH_3)_2SiO(CH_3)_2Si\text{-}Z \qquad (4)$$

where Z is 3-(m-hydroxyphenyl)propyl group.

16. (Previously Presented) The curable silicone composition of Claim 2, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).

17. (Previously Presented) The curable silicone composition of Claim 2, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.

18. (Previously Presented) The curable silicone composition of Claim 2, which is in a liquid or a paste-like form.